

SE10060A  
**N-Channel Enhancement-Mode MOSFET**

Revision: A

#### General Description

Advanced trench technology to provide excellent RDS(ON), low gate charge and low operation voltage. This device is suitable for using as a load switch or in PWM applications.

- Simple Drive Requirement
- Small Package Outline
- Surface Mount Device

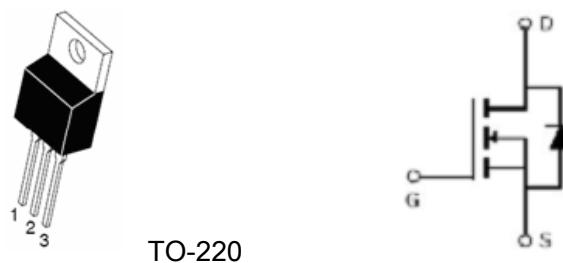
#### Features

For a single MOSFET

- $V_{DS} = 100V$
- $R_{DS(ON)} = 14m\Omega @ V_{GS}=10V$

#### Pin configurations

See Diagram below



#### Absolute Maximum Ratings

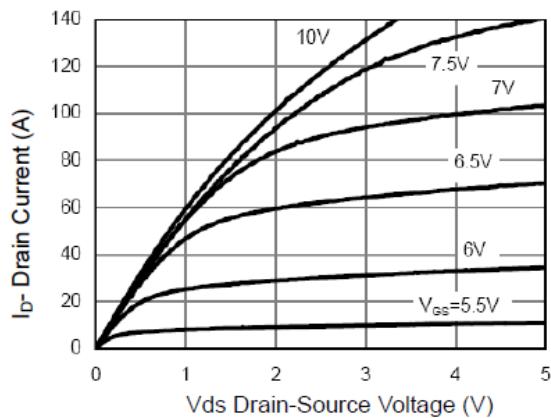
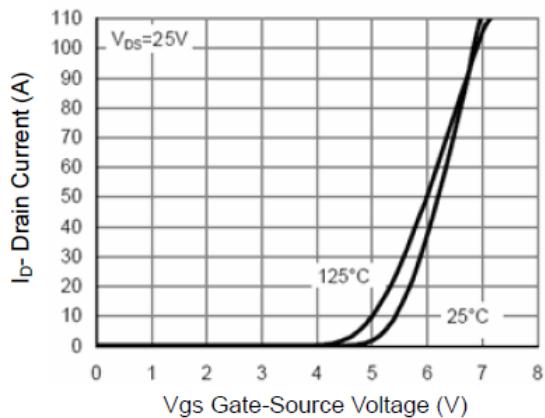
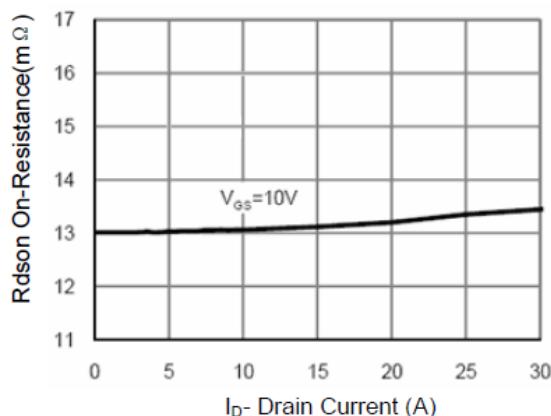
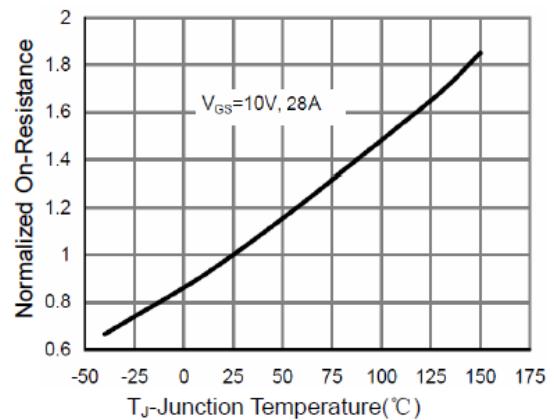
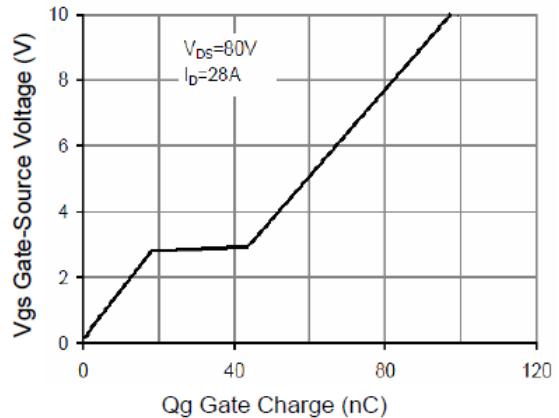
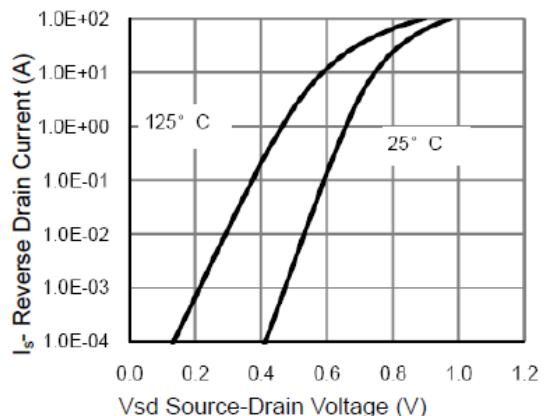
Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current	$I_D$	60	A
Pulsed		200	
Total Power Dissipation @ $T_A=25^\circ C$	$P_D$	170	W
Single-pulse avalanche energy <sup>4</sup>	$E_{AS}$	580	mJ
Operating Junction Temperature Range	$T_J$	-55 to 150	°C

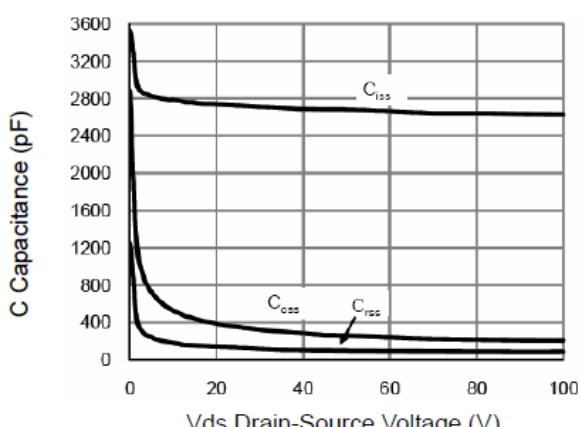
#### Thermal Resistance

Symbol	Parameter	Min	Typ	Units
$R_{\theta JA}$	Junction to Ambient		0.88	°C/W

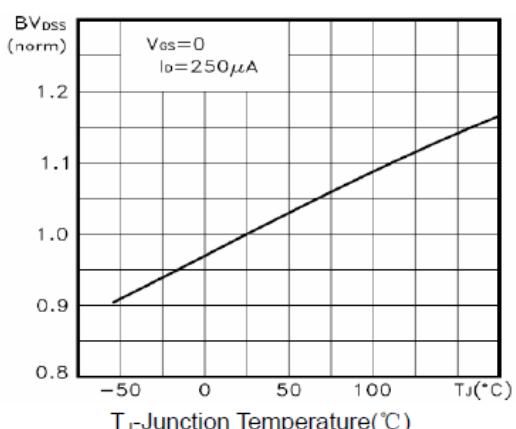
# SE10060A

Electrical Characteristics (T <sub>J</sub> =25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS (Note 2)</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250µA, V <sub>GS</sub> =0 V	100			V
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> = 100V, V <sub>GS</sub> =0V			1	µA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =20 V			100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250µA	2	3	4	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =40A		14	17	mΩ
g <sub>F</sub>	Forward Transconductance	V <sub>DS</sub> = 25V, I <sub>D</sub> =28A	32			S
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1MHz		3400		pF
C <sub>oss</sub>	Output Capacitance			260		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			210		pF
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge <sup>2</sup>	V <sub>DD</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =30A		94		nC
Q <sub>gs</sub>	Gate Source Charge			16		nC
Q <sub>gd</sub>	Gate Drain Charge			24		nC
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =2A, R <sub>GEN</sub> =2.5Ω		15		ns
t <sub>d(off)</sub>	Turn-Off Delay Time			52		ns
t <sub>d(r)</sub>	Turn-On Rise Time			11		ns
t <sub>d(f)</sub>	Turn-Off Fall Time			13		ns
<b>Source-Drain Characteristics</b>						
Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V <sub>SD</sub>	Diode forward voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =100A		0.85	1.2	V
I <sub>S</sub>	Diode forward current				60	A
T <sub>rr</sub>	Reverse recovery time <sup>7</sup>	T <sub>J</sub> =25°C, I <sub>F</sub> =28A di/dt=100A/µs		33		ns
Q <sub>rr</sub>	Reverse recovery charge <sup>7</sup>			54		nC

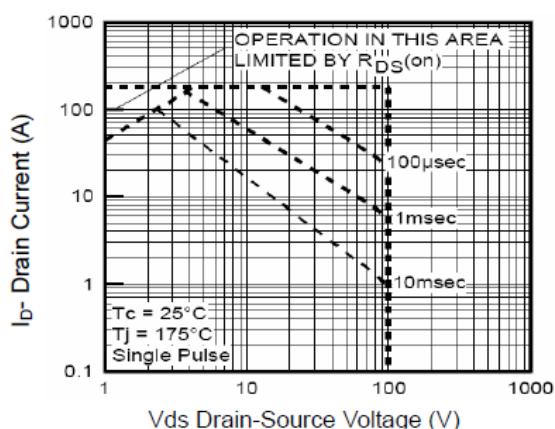
**Typical Characteristics****Figure 1 Output Characteristics****Figure 2 Transfer Characteristics****Figure 3 Rdson- Drain Current****Figure 4 Rdson-JunctionTemperature****Figure 5 Gate Charge****Figure 6 Source- Drain Diode Forward**



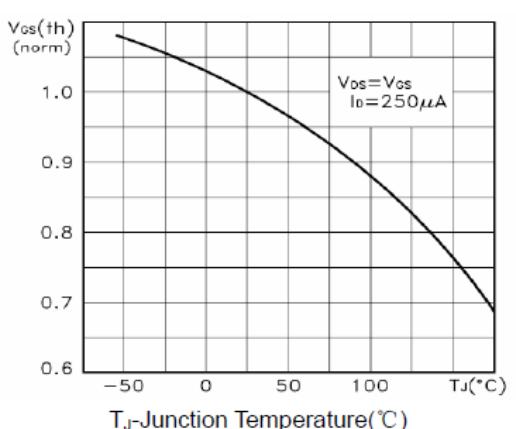
**Figure 7 Capacitance vs Vds**



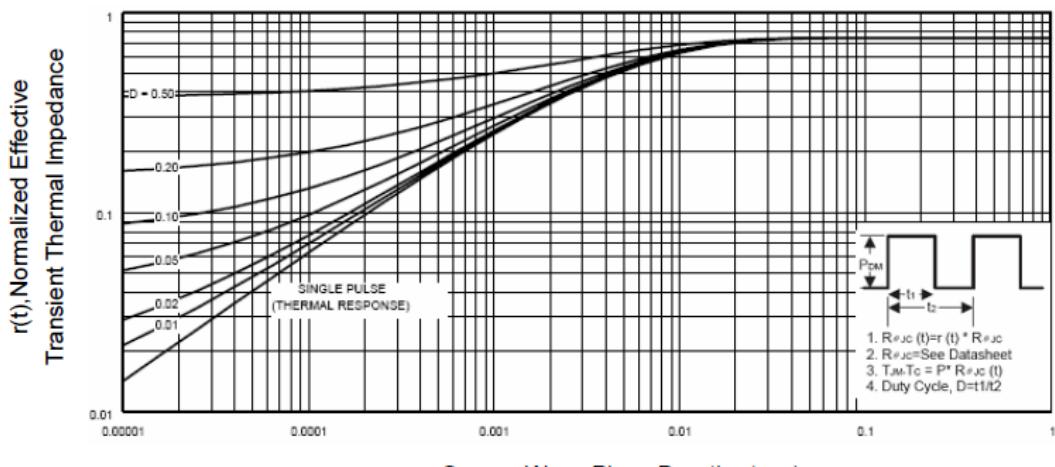
**Figure 9  $BV_{DSS}$  vs Junction Temperature**



**Figure 8 Safe Operation Area**



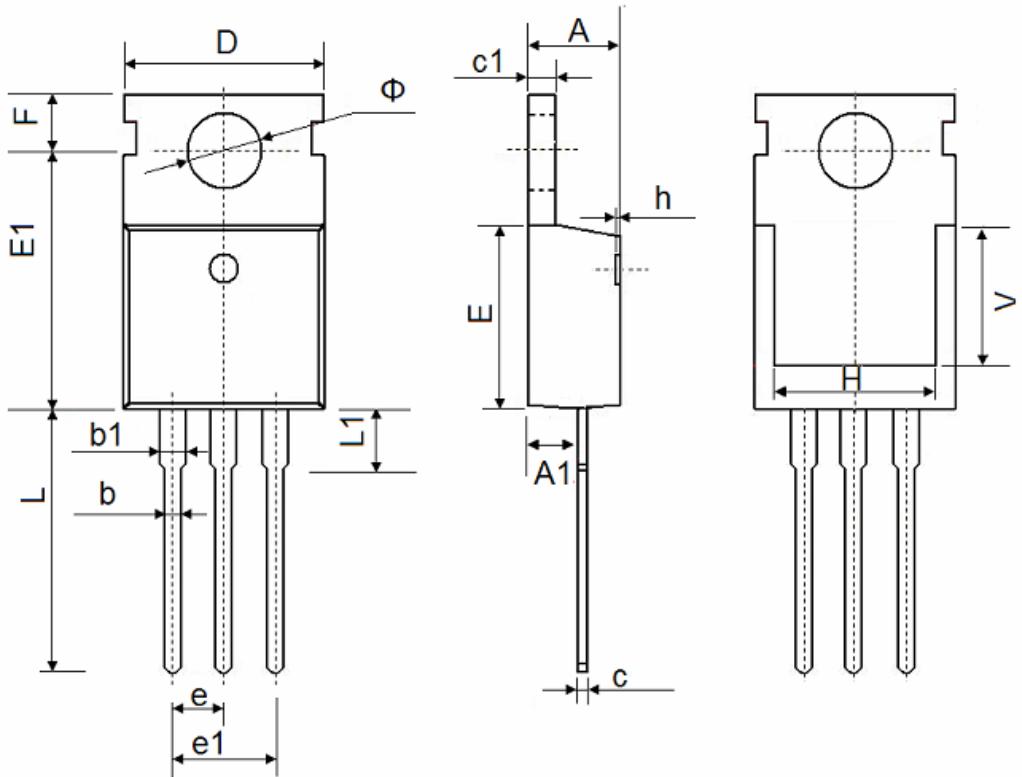
**Figure 10  $V_{GS(\text{th})}$  vs Junction Temperature**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## Package Outline Dimension

TO-220



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150

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